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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

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Details	
Product Status	Obsolete
Core Processor	Н8/300Н
Core Size	16-Bit
Speed	20MHz
Connectivity	SCI
Peripherals	PWM, WDT
Number of I/O	30
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 4x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/df36012fpwv

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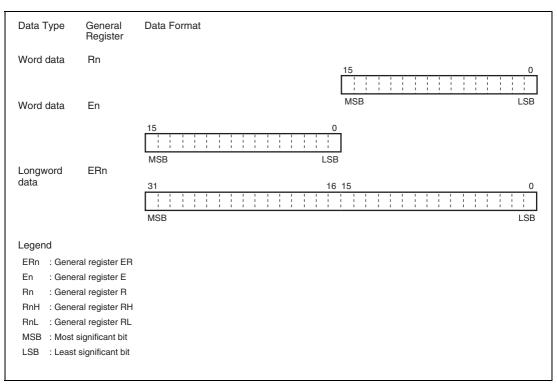


Figure 2.5 General Register Data Formats (2)



2.3.2 Memory Data Formats

Figure 2.6 shows the data formats in memory. The H8/300H CPU can access word data and longword data in memory, however word or longword data must begin at an even address. If an attempt is made to access word or longword data at an odd address, an address error does not occur, however the least significant bit of the address is regarded as 0, so access begins the preceding address. This also applies to instruction fetches.

When ER7 (SP) is used as an address register to access the stack, the operand size should be word or longword.

Data Type	Address	Data Format
		7 0
1-bit data	Address L	7 6 5 4 3 2 1 0
Byte data	Address L	MSB LLSB
Word data	Address 2M Address 2M+1	MSB'
Longword data	Address 2N Address 2N+1	MSB
	Address 2N+2 Address 2N+3	

Figure 2.6 Memory Data Formats

The access ranges of absolute addresses for the group of this LSI are those shown in table 2.11, because the upper 8 bits are ignored.

Absolute Address	Access Range
8 bits (@aa:8)	H'FF00 to H'FFFF
16 bits (@aa:16)	H'0000 to H'FFFF
24 bits (@aa:24)	H'0000 to H'FFFF

Table 2.11 Absolute Address Access Ranges

(6) Immediate—#xx:8, #xx:16, or #xx:32

The instruction contains 8-bit (#xx:8), 16-bit (#xx:16), or 32-bit (#xx:32) immediate data as an operand.

The ADDS, SUBS, INC, and DEC instructions contain immediate data implicitly. Some bit manipulation instructions contain 3-bit immediate data in the instruction code, specifying a bit number. The TRAPA instruction contains 2-bit immediate data in its instruction code, specifying a vector address.

(7) Program-Counter Relative—@(d:8, PC) or @(d:16, PC)

This mode is used in the BSR instruction. An 8-bit or 16-bit displacement contained in the instruction is sign-extended and added to the 24-bit PC contents to generate a branch address. The PC value to which the displacement is added is the address of the first byte of the next instruction, so the possible branching range is -126 to +128 bytes (-63 to +64 words) or -32766 to +32768 bytes (-16383 to +16384 words) from the branch instruction. The resulting value should be an even number.

(8) Memory Indirect—@@aa:8

This mode can be used by the JMP and JSR instructions. The instruction code contains an 8-bit absolute address specifying a memory operand. This memory operand contains a branch address. The memory operand is accessed by longword access. The first byte of the memory operand is ignored, generating a 24-bit branch address. Figure 2.8 shows how to specify branch address for in memory indirect mode. The upper bits of the absolute address are all assumed to be 0, so the address range is 0 to 255 (H'0000 to H'00FF).

Note that the first part of the address range is also the exception vector area.





P80/FTCI pin

Register	PCR8	
Bit Name	PCR80	Pin Function
Setting Value	0	P80 input/FTCI input pin
	1	P80 output/FTCI input pin

9.6 Port B

Port B is an input port also functioning as an A/D converter analog input pin. Each pin of the port B is shown in figure 9.6.

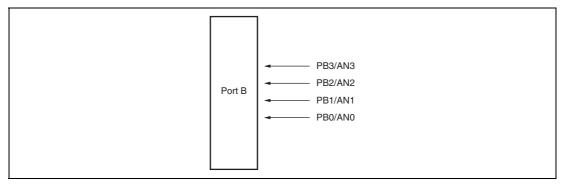


Figure 9.6 Port B Pin Configuration

Port B has the following register.

• Port data register B (PDRB)



TCRV0			TCRV1	
Bit 2	Bit 1	Bit 0	Bit 0	
CKS2	CKS1	CKS0	ICKS0	Description
0	0	0	_	Clock input prohibited
		1	0	Internal clock: counts on $\phi/4$, falling edge
			1	Internal clock: counts on $\phi/8$, falling edge
	1	0	0	Internal clock: counts on $\phi/16$, falling edge
			1	Internal clock: counts on $\phi/32$, falling edge
		1	0	Internal clock: counts on $\phi/64$, falling edge
			1	Internal clock: counts on $\phi/128$, falling edge
1	0	0		Clock input prohibited
		1		External clock: counts on rising edge
	1	0		External clock: counts on falling edge
		1		External clock: counts on rising and falling edge

Table 10.2 Clock Signals to Input to TCNTV and Counting Conditions

Bit	Bit Name	Initial Value	R/W	Description
0	TOA	0	R/W	Timer Output Level Setting A
				Sets the output value of the FTIOA pin until the first compare match A is generated.
				0: Output value is 0*
				1: Output value is 1*

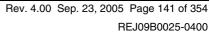
Legend X: Don't care.

Note: * The change of the setting is immediately reflected in the output value.

11.3.3 Timer Interrupt Enable Register W (TIERW)

TIERW controls the timer W interrupt request.

		Initial		
Bit	Bit Name	Value	R/W	Description
7	OVIE	0	R/W	Timer Overflow Interrupt Enable
				When this bit is set to 1, FOVI interrupt requested by OVF flag in TSRW is enabled.
6 to 4	_	All 1	—	Reserved
				These bits are always read as 1.
3	IMIED	0	R/W	Input Capture/Compare Match Interrupt Enable D
				When this bit is set to 1, IMID interrupt requested by IMFD flag in TSRW is enabled.
2	IMIEC	0	R/W	Input Capture/Compare Match Interrupt Enable C
				When this bit is set to 1, IMIC interrupt requested by IMFC flag in TSRW is enabled.
1	IMIEB	0	R/W	Input Capture/Compare Match Interrupt Enable B
				When this bit is set to 1, IMIB interrupt requested by IMFB flag in TSRW is enabled.
0	IMIEA	0	R/W	Input Capture/Compare Match Interrupt Enable A
				When this bit is set to 1, IMIA interrupt requested by IMFA flag in TSRW is enabled.



13.3.7 Serial Status Register (SSR)

SSR is a register containing status flags of the SCI3 and multiprocessor bits for transfer. 1 cannot be written to flags TDRE, RDRF, OER, PER, and FER; they can only be cleared.

Bit	Bit Name	Initial Value	R/W	Description
7	TDRE	1	R/W	Transmit Data Register Empty
				Indicates whether TDR contains transmit data.
				[Setting conditions]
				When the TE bit in SCR3 is 0
				When data is transferred from TDR to TSR
				[Clearing conditions]
				• When 0 is written to TDRE after reading TDRE = 1
				When the transmit data is written to TDR
6	RDRF	0	R/W	Receive Data Register Full
				Indicates that the received data is stored in RDR.
				[Setting condition]
				 When serial reception ends normally and receive data is transferred from RSR to RDR
				[Clearing conditions]
				• When 0 is written to RDRF after reading RDRF = 1
				When data is read from RDR
5	OER	0	R/W	Overrun Error
				[Setting condition]
				When an overrun error occurs in reception
				[Clearing condition]
				 When 0 is written to OER after reading OER = 1
4	FER	0	R/W	Framing Error
				[Setting condition]
				When a framing error occurs in reception
				[Clearing condition]
				• When 0 is written to FER after reading FER = 1

13.4.4 Serial Data Reception

Figure 13.7 shows an example of operation for reception in asynchronous mode. In serial reception, the SCI3 operates as described below.

- 1. The SCI3 monitors the communication line. If a start bit is detected, the SCI3 performs internal synchronization, receives receive data in RSR, and checks the parity bit and stop bit.
- 2. If an overrun error occurs (when reception of the next data is completed while the RDRF flag is still set to 1), the OER bit in SSR is set to 1. If the RIE bit in SCR3 is set to 1 at this time, an ERI interrupt request is generated. Receive data is not transferred to RDR.
- 3. If a parity error is detected, the PER bit in SSR is set to 1 and receive data is transferred to RDR. If the RIE bit in SCR3 is set to 1 at this time, an ERI interrupt request is generated.
- 4. If a framing error is detected (when the stop bit is 0), the FER bit in SSR is set to 1 and receive data is transferred to RDR. If the RIE bit in SCR3 is set to 1 at this time, an ERI interrupt request is generated.
- 5. If reception is completed successfully, the RDRF bit in SSR is set to 1, and receive data is transferred to RDR. If the RIE bit in SCR3 is set to 1 at this time, an RXI interrupt request is generated. Continuous reception is possible because the RXI interrupt routine reads the receive data transferred to RDR before reception of the next receive data has been completed.

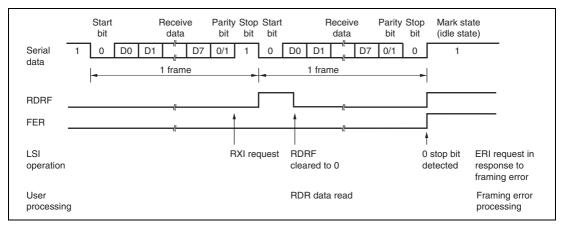


Figure 13.7 Example of SCI3 Reception in Asynchronous Mode (8-Bit Data, Parity, One Stop Bit)

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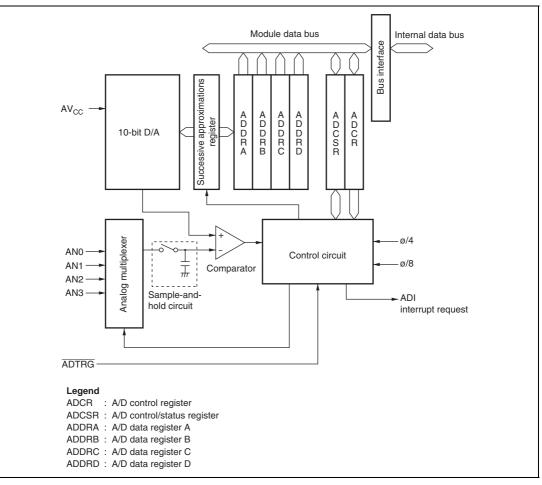


Figure 14.1 Block Diagram of A/D Converter



14.2 Input/Output Pins

Table 14.1 summarizes the input pins used by the A/D converter.

Table 14.1 Pin Configuration

Pin Name	Symbol	I/O	Function
Analog power supply pin	AV_{cc}	Input	Analog block power supply pin
Analog input pin 0	AN0	Input	Analog input pins
Analog input pin 1	AN1	Input	
Analog input pin 2	AN2	Input	
Analog input pin 3	AN3	Input	
A/D external trigger input pin	ADTRG	Input	External trigger input pin for starting A/D conversion



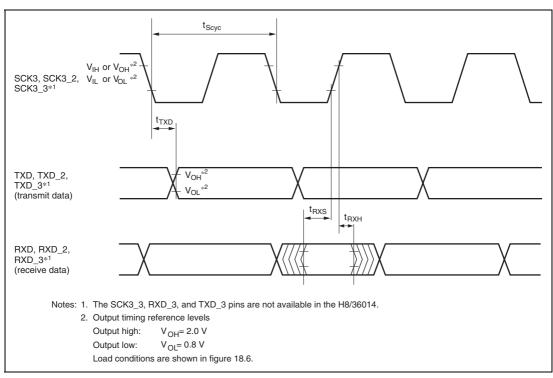
		Initial			
Bit	Bit Name	Value	R/W	Description	
2	CH2	0	R/W	Channel Select 0 to 2	
1	CH1	0	R/W	Select analog input chan	nels.
0	CH0	0	R/W	When SCAN = 0	When SCAN = 1
				X00: AN0	X00: AN0
				X01: AN1	X01: AN0 to AN1
				X10: AN2	X10: AN0 to AN2
				X11: AN3	X11: AN0 to AN3

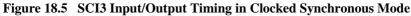
Legend X: Don't care.

14.3.3 A/D Control Register (ADCR)

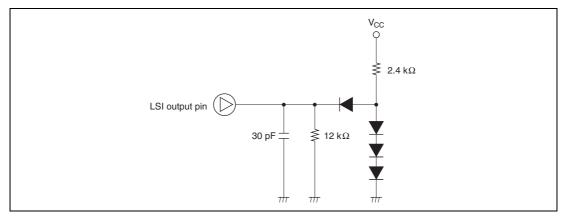
ADCR enables A/D conversion started by an external trigger signal.

Bit	Bit Name	Initial Value	R/W	Description
7	TRGE	0	R/W	Trigger Enable
				A/D conversion is started at the falling edge and the rising edge of the external trigger signal (ADTRG) when this bit is set to 1.
				The selection between the falling edge and rising edge of the external trigger pin (ADTRG) conforms to the WPEG5 bit in the interrupt edge select register 2 (IEGR2)
6 to 1	_	All 1	_	Reserved
				These bits are always read as 1.
0	_	0	R/W	Reserved
				Do not set this bit to 1, though the bit is readable/writable.





18.5 Output Load Condition





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Table A.2 Operation Code Map (3)

A.3 Number of Execution States

The status of execution for each instruction of the H8/300H CPU and the method of calculating the number of states required for instruction execution are shown below. Table A.4 shows the number of cycles of each type occurring in each instruction, such as instruction fetch and data read/write. Table A.3 shows the number of states required for each cycle. The total number of states required for execution of an instruction can be calculated by the following expression:

Execution states = $I \times S_1 + J \times S_2 + K \times S_K + L \times S_L + M \times S_M + N \times S_N$

Examples: When instruction is fetched from on-chip ROM, and an on-chip RAM is accessed.

BSET #0, @FF00

From table A.4: $I=L=2, \quad J=K=M=N{=}0$

From table A.3: $S_1 = 2$, $S_1 = 2$

Number of states required for execution $= 2 \times 2 + 2 \times 2 = 8$

When instruction is fetched from on-chip ROM, branch address is read from on-chip ROM, and on-chip RAM is used for stack area.

JSR @@ 30

From table A.4: $I=2, \quad J=K=1, \quad L=M=N=0$

From table A.3:

$$\mathbf{S}_{\mathrm{I}} = \mathbf{S}_{\mathrm{J}} = \mathbf{S}_{\mathrm{K}} = 2$$

Number of states required for execution = $2 \times 2 + 1 \times 2 + 1 \times 2 = 8$



Appendix B I/O Port Block Diagrams

B.1 I/O Port Block Diagrams

 $\overline{\text{RES}}$ goes low in a reset, and $\overline{\text{SBY}}$ goes low in a reset and in standby mode.

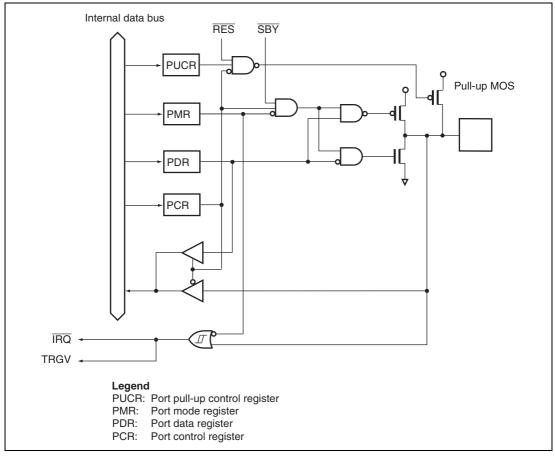


Figure B.1 Port 1 Block Diagram (P17)



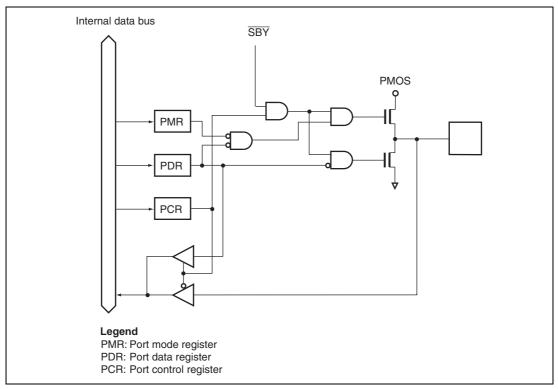


Figure B.9 Port 5 Block Diagram (P57, P56) (H8/36014)



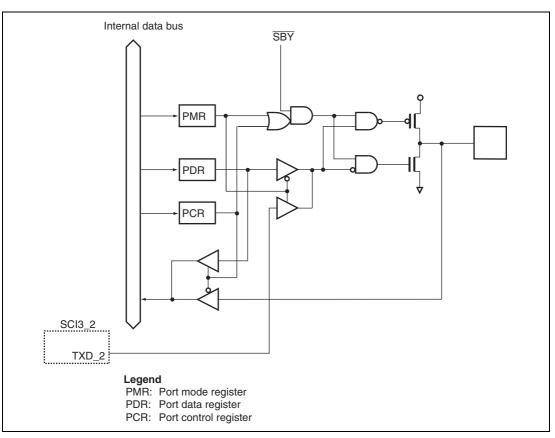


Figure B.18 Port 7 Block Diagram (P72)

